

$V_{DSS}$	100V
$R_{DS(on)}(Max.)$	1.86m $\Omega$
$I_D$	$\pm 300A$
$P_D$	340W

### ●Features

- 1) Low on - resistance
- 2) High power package  
(DFN8080)
- 3) Pb-free plating ; RoHS compliant
- 4) Halogen Free
- 5) 100% Rg and UIS tested
- 6) Wide-SOA

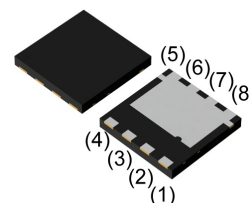
### ●Application

Hot Swap Controller(HSC)

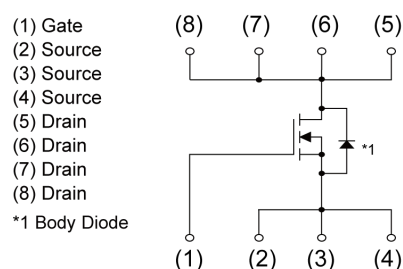
### ●Outline

DFN8080-8S

DFN8080T8LSHAAI



### ●Inner circuit



### ●Packaging specifications

Type	Packing	Embossed Tape
	Reel size (mm)	330
	Tape width (mm)	16
	Quantity (pcs)	2500
	Taping code	TBC
	Marking	RY7P250BM

### ●Absolute maximum ratings ( $T_a = 25^\circ C$ ,unless otherwise specified)

Parameter		Symbol	Value	Unit
Drain - Source voltage		$V_{DSS}$	100	V
Continuous drain current	Silicon limit ( $V_{GS}=10V$ )	$I_D^{*1}$	$\pm 300$	A
	$T_c = 25^\circ C$ ( $V_{GS}=10V$ )	$I_D^{*2}$	$\pm 250$	A
Pulsed drain current		$I_{DP}^{*3}$	$\pm 900$	A
Gate - Source voltage		$V_{GSS}$	$\pm 20$	V
Avalanche current, single pulse		$I_{AS}^{*4}$	79	A
Avalanche energy, single pulse		$E_{AS}^{*4}$	497	mJ
Power dissipation		$P_D^{*2}$	340	W
Junction temperature		$T_j$	175	$^\circ C$
Operating junction and storage temperature range		$T_{stg}$	-55 to +175	$^\circ C$

### ● Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - case	$R_{thJC}^{*2}$	-	-	0.44	°C/W
Thermal resistance, junction - ambient	$R_{thJA}^{*5}$	-	35	-	°C/W

### ● Electrical characteristics ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 1mA$	100	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	$I_D = 1mA$ referenced to $25^\circ\text{C}$	-	58.4	-	mV/°C
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 100V, V_{GS} = 0V$	-	-	5	μA
Gate - Source leakage current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±500	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 1mA$	2.0	-	4.0	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	$I_D = 1mA$ referenced to $25^\circ\text{C}$	-	-5.6	-	mV/°C
Static drain - source on - state resistance	$R_{DS(on)}^{*6}$	$V_{GS} = 10V, I_D = 50A$	-	1.43	1.86	mΩ
Gate resistance	$R_G$	-	0.9	1.9	3.8	Ω
Forward Transfer Admittance	$ Y_{fs} ^{*6}$	$V_{DS} = 5V, I_D = 50A$	27	-	-	S

\*1 Limited by silicon chip capability.

\*2  $T_c = 25^\circ\text{C}$ , Limited only by maximum temperature allowed.

\*3  $P_w \leq 10\mu s$ , Duty cycle  $\leq 1\%$

\*4  $L \approx 0.1mH$ ,  $V_{DD} = 50V$ ,  $R_G = 25\Omega$ , Starting  $T_j = 25^\circ\text{C}$  Fig.3-1,3-2

\*5 Mounted on Cu board (25.4mm×25.4mm×70μm)

\*6 Pulsed

**●Electrical characteristics** ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Input capacitance	$C_{iss}$	$V_{GS} = 0V$	*6780	11300	*15900	pF
Output capacitance	$C_{oss}$	$V_{DS} = 50V$	*1060	1760	*2470	
Reverse transfer capacitance	$C_{rss}$	$f = 1\text{MHz}$	*28	55	*110	
Turn - on delay time	$t_{d(on)}^{*6}$	$V_{DD} \approx 50V, V_{GS} = 10V$	-	72	-	ns
Rise time	$t_r^{*6}$	$I_D = 50A$	-	90	-	
Turn - off delay time	$t_{d(off)}^{*6}$	$R_L \approx 1\Omega$	-	195	-	
Fall time	$t_f^{*6}$	$R_G = 10\Omega$	-	200	-	

\*: Guarantee of Design

**●Gate charge characteristics** ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Total gate charge	$Q_g^{*6}$	$V_{DD} \approx 50V,$	*105	170	*240	nC
Gate - Source charge	$Q_{gs}^{*6}$	$I_D = 50A,$	*32	53	*75	
Gate - Drain charge	$Q_{gd}^{*6}$	$V_{GS} = 10V$	*15	29	*58	

\*: Guarantee of Design

**●Body diode electrical characteristics** (Source-Drain) ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Continuous forward current	$I_S^{*2}$	-	-	-	250	A
Pulse forward current	$I_{SP}^{*3}$		-	-	900	A
Forward voltage	$V_{SD}^{*6}$	$V_{GS} = 0V, I_S = 50A$	-	-	1.2	V
Reverse recovery time	$t_{rr}^{*6}$	$I_S = 50A, V_{GS}=0V$	-	99	-	ns
Reverse recovery charge	$Q_{rr}^{*6}$	$di/dt = 100A/\mu s$	-	295	-	nC

## ●Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

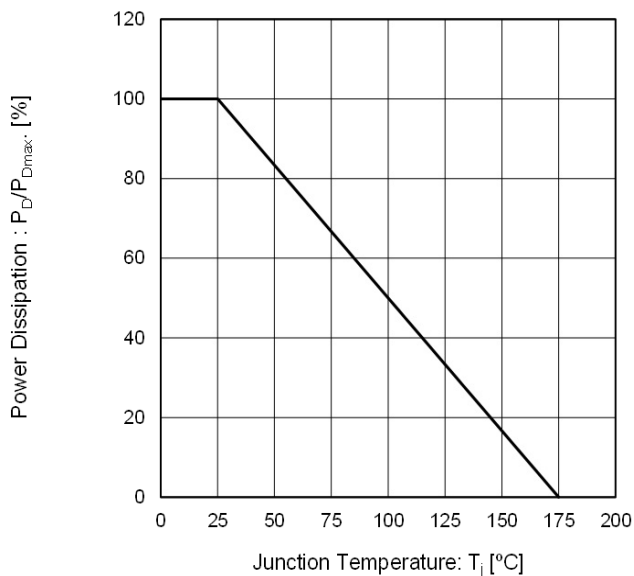


Fig.2 Maximum Safe Operating Area

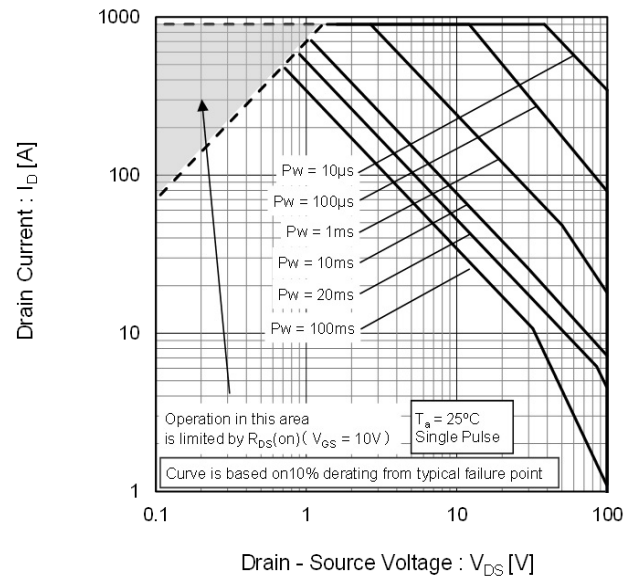


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

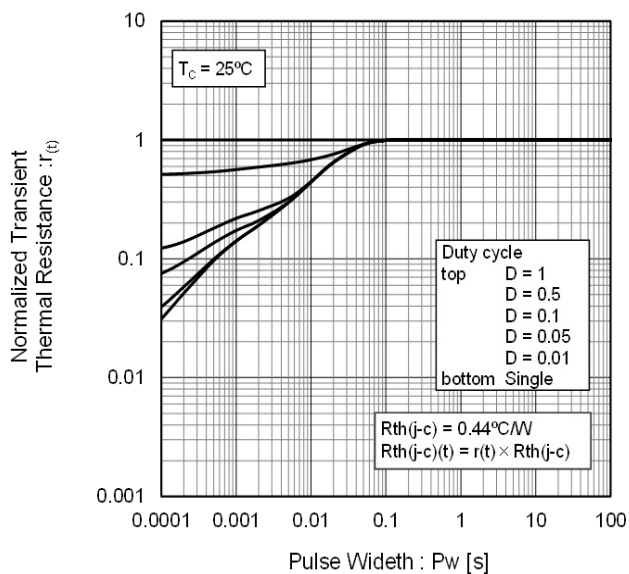
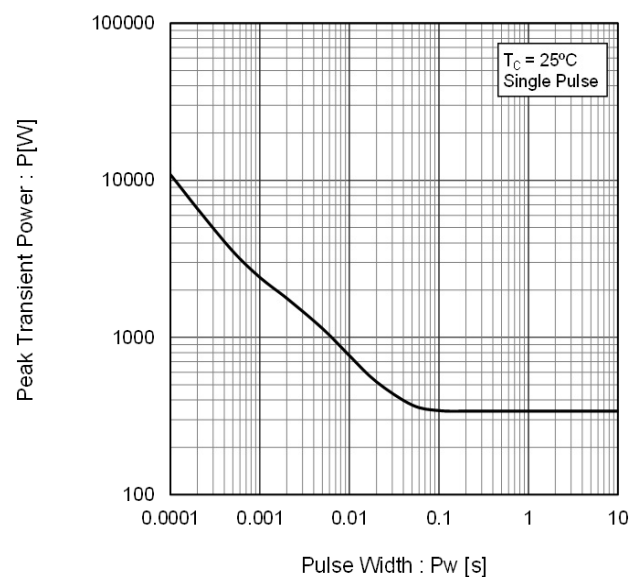


Fig.4 Single Pulse Maximum Power Dissipation



## ●Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

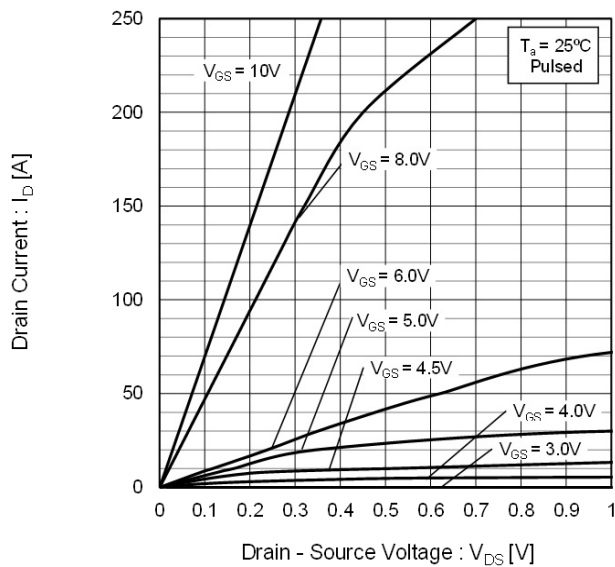


Fig.6 Typical Output Characteristics(II)

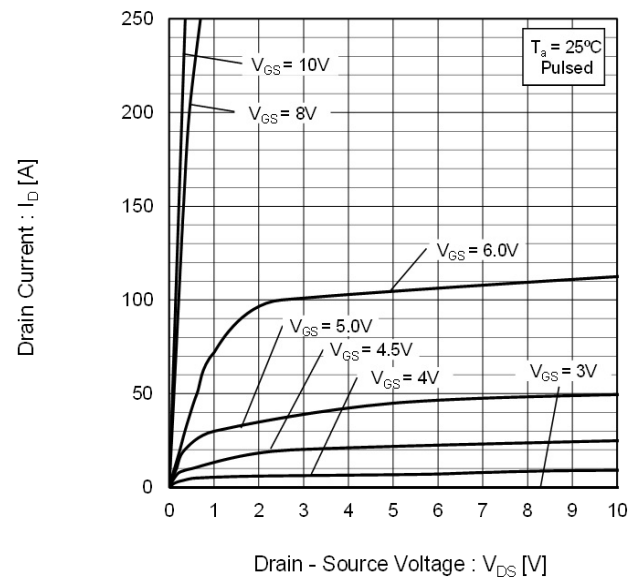


Fig.7 Normalized Breakdown Voltage vs. Junction Temperature

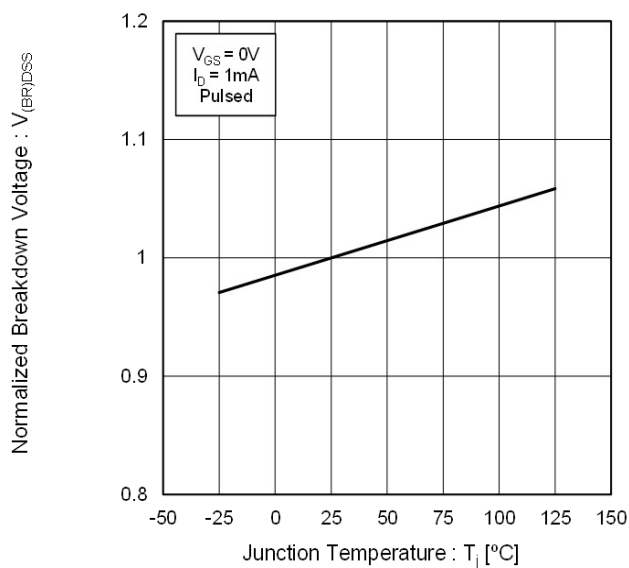
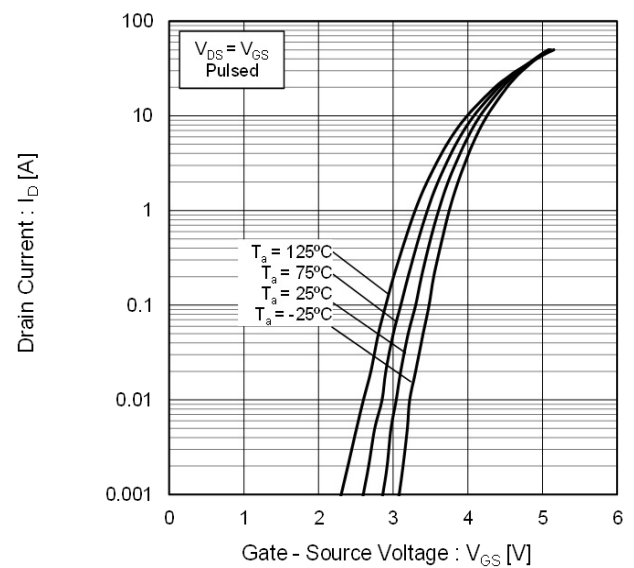


Fig.8 Typical Transfer Characteristics



●Electrical characteristic curves

Fig.9 Gate Threshold Voltage vs. Junction Temperature

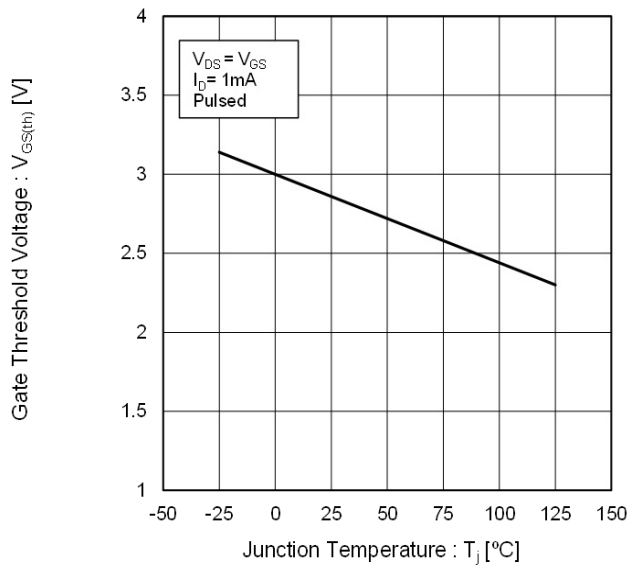


Fig.10 Forward Transfer Admittance vs. Drain Current

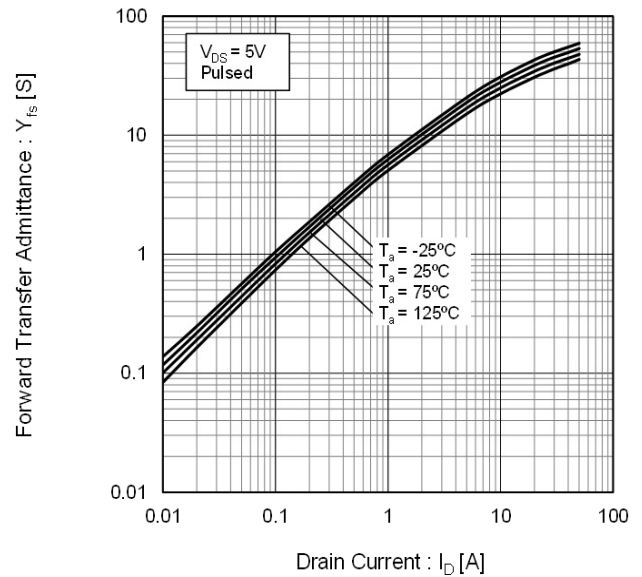


Fig.11 Drain Current Derating Curve

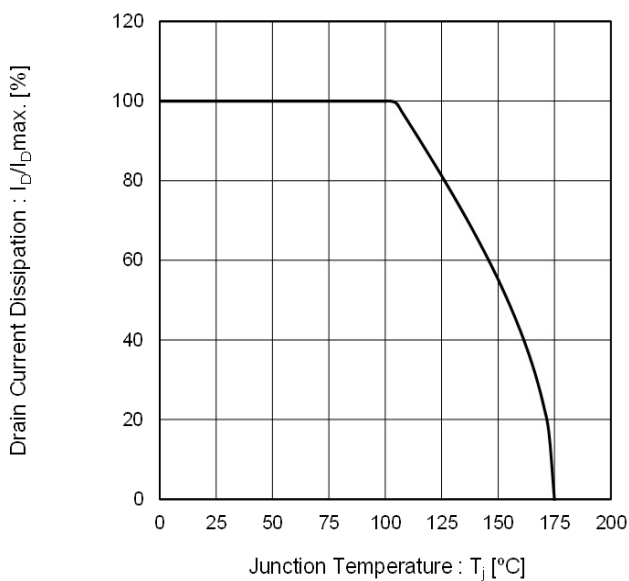
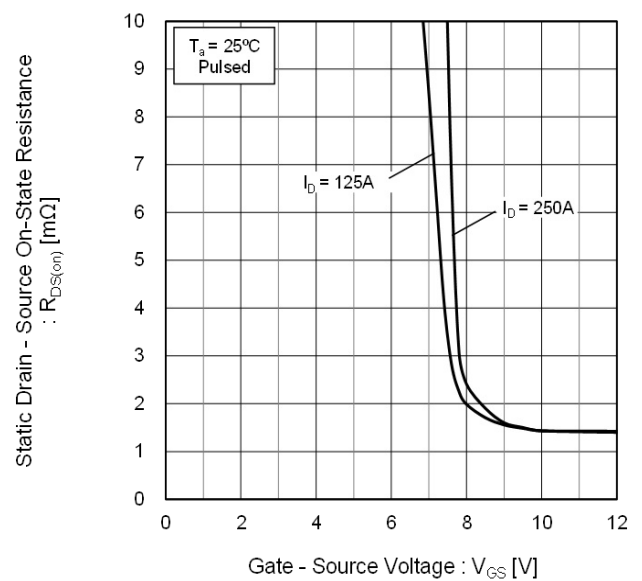


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



## ●Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

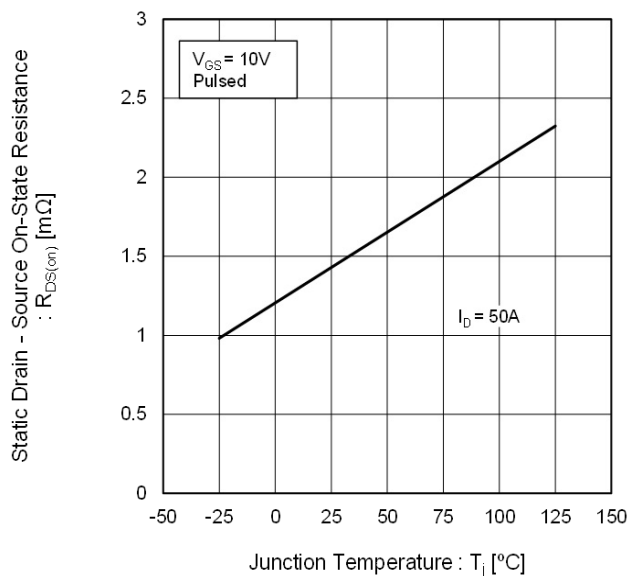


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current

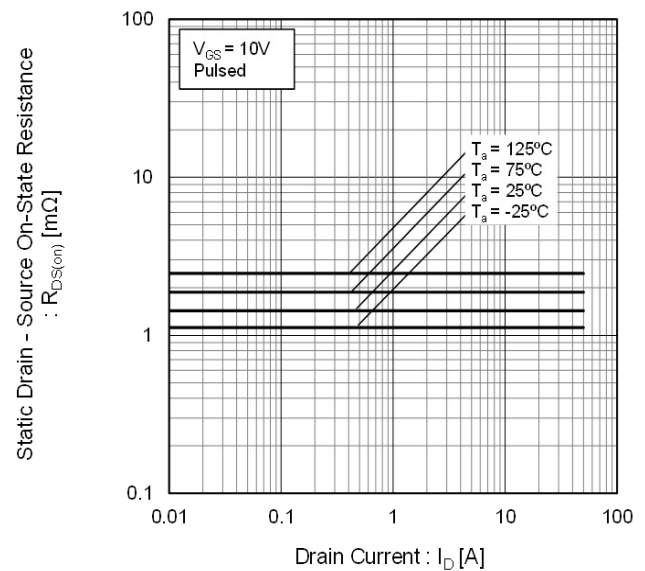


Fig.15 Typical Capacitances vs. Drain - Source Voltage

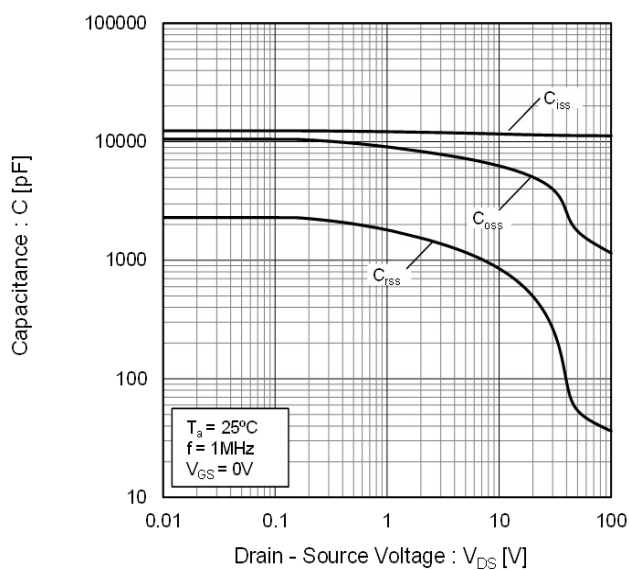
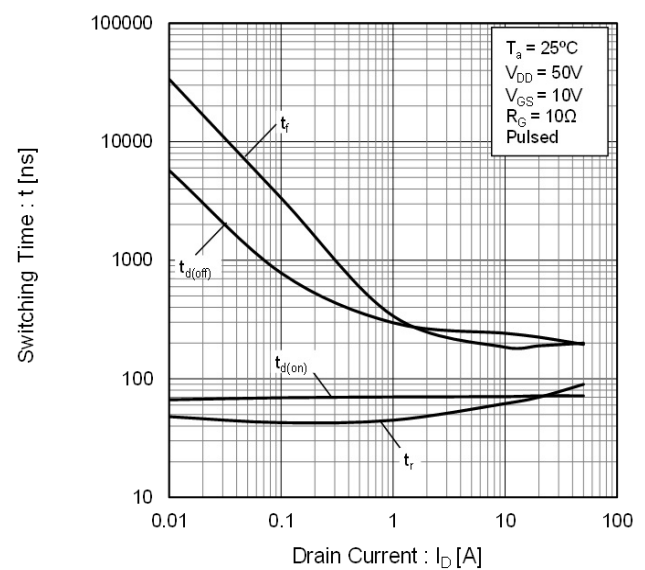


Fig.16 Switching Characteristics



●Electrical characteristic curves

Fig.17 Typical Gate Charge

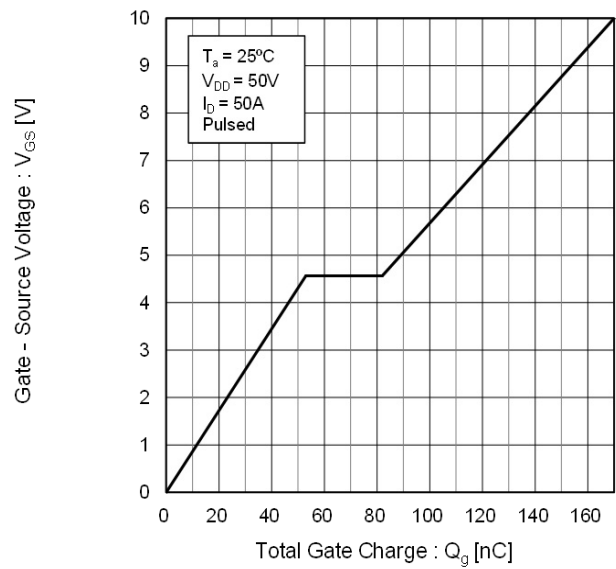
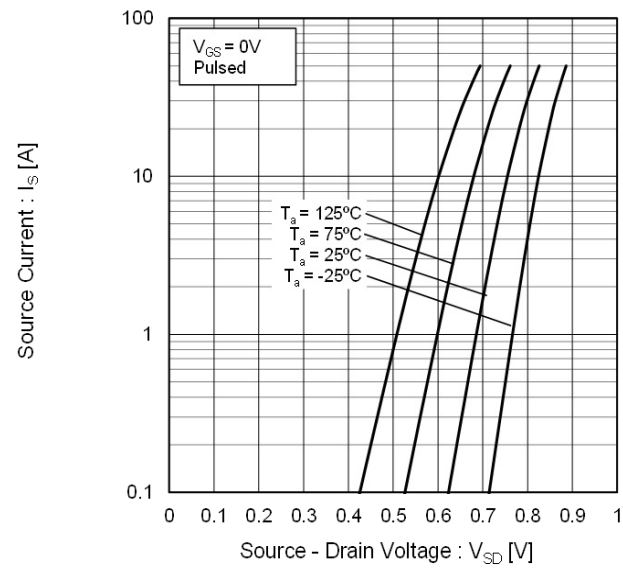


Fig.18 Source Current vs. Source Drain Voltage





## ● Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

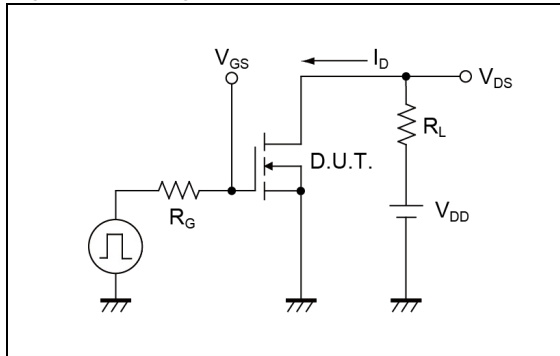


Fig.1-2 Switching Waveforms

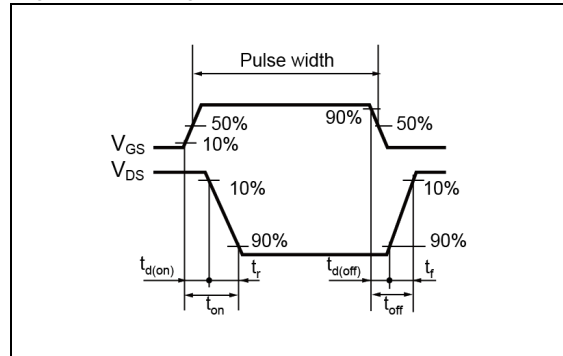


Fig.2-1 Gate Charge Measurement Circuit

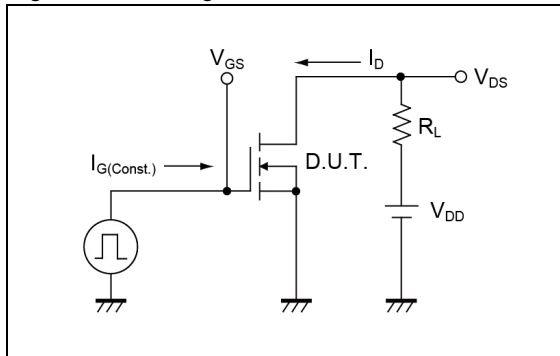


Fig.2-2 Gate Charge Waveform

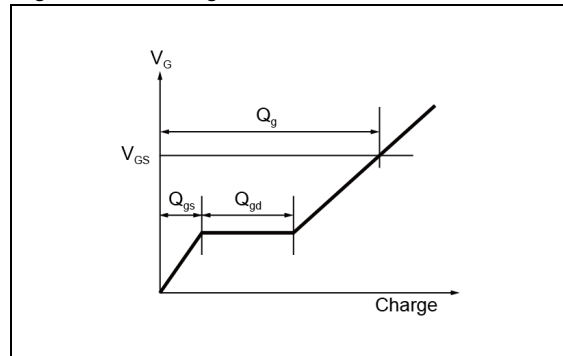


Fig.3-1 Avalanche Measurement Circuit

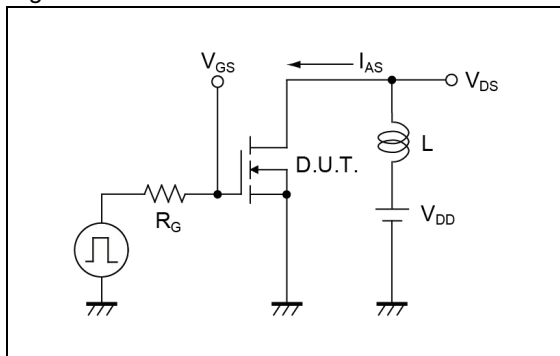
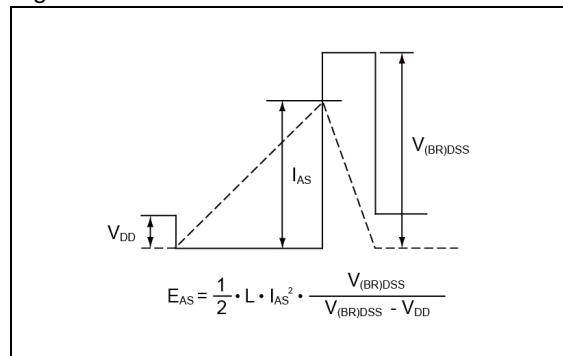
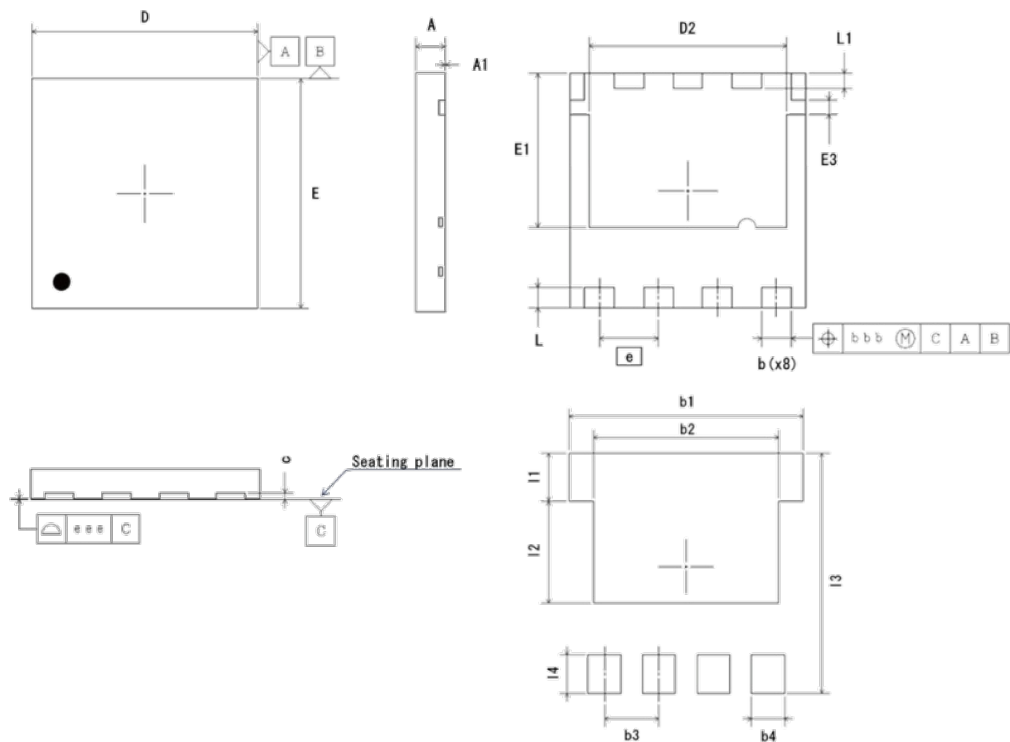


Fig.3-2 Avalanche Waveform



●Dimensions

DFN8080-8S  
 (DFN8080T8LSHAAI)



Referenced footprint dimensions

DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.90	1.10	0.035	0.043
A1	0.00	0.05	0.000	0.002
b	0.90	1.10	0.035	0.043
c	0.203 REF		0.008 REF	
D	7.90	8.10	0.311	0.319
D2	6.60	6.80	0.260	0.268
E	7.90	8.10	0.311	0.319
E1	5.15	5.35	0.203	0.211
E3	0.40	0.60	0.016	0.024
e	2.00 BSC		0.08 BSC	
L	0.60	0.80	0.024	0.031
L1	0.40	0.60	0.016	0.024
bbb	0.10		0.004	
eee	0.08		0.003	

DIM	Millimeters	Inches
	Nom.	Nom.
b1	8.60	0.339
b2	6.80	0.268
b3	2.00	0.079
b4	1.20	0.047
I1	1.76	0.069
I2	3.74	0.147
I3	8.80	0.346
I4	1.40	0.055

Dimension in mm/inches

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JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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  - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - Sealing or coating our Products with resin or other coating materials
  - Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.) ; or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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## Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

## Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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